

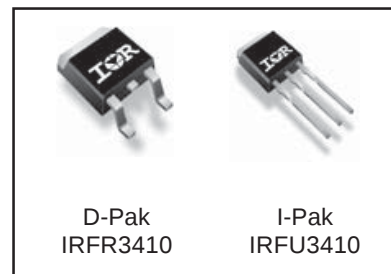
Applications

- High frequency DC-DC converters

V_{DS}	$R_{DS(on)}$ max	I_D
100V	39m Ω	31A ^⑥

Benefits

- Low Gate-to-Drain Charge to Reduce Switching Losses
- Fully Characterized Capacitance Including Effective C_{OSS} to Simplify Design, (See App. Note AN1001)
- Fully Characterized Avalanche Voltage and Current



Absolute Maximum Ratings

Symbol	Parameter	Max.	Units
V _{DS}	Drain-Source Voltage	100	V
V _{GS}	Gate-to-Source Voltage	± 20	
I _D @ T _C = 25°C	Continuous Drain Current, V _{GS} @ 10V	31⑥	A
I _D @ T _C = 100°C	Continuous Drain Current, V _{GS} @ 10V	22	
I _{DM}	Pulsed Drain Current①	125	
P _D @T _C = 25°C	Maximum Power Dissipation	110	W
P _D @T _A = 25°C	Maximum Power Dissipation	3.0	
	Linear Derating Factor	0.71	
dv/dt	Peak Diode Recovery dv/dt ③	15	mW°C
T _J	Operating Junction and	-55 to + 175	V/ns
T _{STG}	Storage Temperature Range		
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	°C

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	1.4	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Junction-to-Ambient (PCB mount)*	—	40	
$R_{\theta JA}$	Junction-to-Ambient	—	110	

Notes ① through ⑥ are on page 10

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Static @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	100	—	—	V	$V_{GS} = 0V$, $I_D = 250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.11	—	$V/^\circ\text{C}$	Reference to 25°C , $I_D = 1mA$ ④
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	34	39	$m\Omega$	$V_{GS} = 10V$, $I_D = 18A$ ④
$V_{GS(th)}$	Gate Threshold Voltage	2.0	—	4.0	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$
I_{DSS}	Drain-to-Source Leakage Current	—	—	20	μA	$V_{DS} = 100V$, $V_{GS} = 0V$
		—	—	250		$V_{DS} = 80V$, $V_{GS} = 0V$, $T_J = 150^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	200	nA	$V_{GS} = 20V$
	Gate-to-Source Reverse Leakage	—	—	-200		$V_{GS} = -20V$

Dynamic @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
g_{fs}	Forward Transconductance	33	—	—	S	$V_{DS} = 25V$, $I_D = 18A$
Q_g	Total Gate Charge	—	37	56	nC	$I_D = 18A$ $V_{DS} = 50V$ $V_{GS} = 10V$, ④
Q_{gs}	Gate-to-Source Charge	—	10	—		
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	11	—		
$t_{d(on)}$	Turn-On Delay Time	—	12	—	ns	$V_{DD} = 50V$ $I_D = 18A$ $R_G = 9.1\Omega$ $V_{GS} = 10V$ ④
t_r	Rise Time	—	27	—		
$t_{d(off)}$	Turn-Off Delay Time	—	40	—		
t_f	Fall Time	—	13	—		
C_{iss}	Input Capacitance	—	1690	—	pF	$V_{GS} = 0V$
C_{oss}	Output Capacitance	—	220	—		$V_{DS} = 25V$
C_{rss}	Reverse Transfer Capacitance	—	26	—		$f = 1.0MHz$
C_{oss}	Output Capacitance	—	1640	—		$V_{GS} = 0V$, $V_{DS} = 1.0V$, $f = 1.0MHz$
C_{oss}	Output Capacitance	—	130	—		$V_{GS} = 0V$, $V_{DS} = 80V$, $f = 1.0MHz$
$C_{oss \text{ eff.}}$	Effective Output Capacitance	—	250	—		$V_{GS} = 0V$, $V_{DS} = 0V$ to $80V$ ⑤

Avalanche Characteristics

	Parameter	Typ.	Max.	Units
E_{AS}	Single Pulse Avalanche Energy②	—	140	mJ
I_{AR}	Avalanche Current①	—	18	A

Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	31⑥	A	MOSFET symbol showing the integral reverse p-n junction diode.
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	125		
V_{SD}	Diode Forward Voltage	—	—	1.3	V	$T_J = 25^\circ\text{C}$, $I_S = 18A$, $V_{GS} = 0V$ ④
t_{rr}	Reverse Recovery Time	—	84	—	ns	$T_J = 25^\circ\text{C}$, $I_F = 18A$
Q_{rr}	Reverse Recovery Charge	—	260	—	nC	$di/dt = 100A/\mu s$ ④
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S + L_D$)				

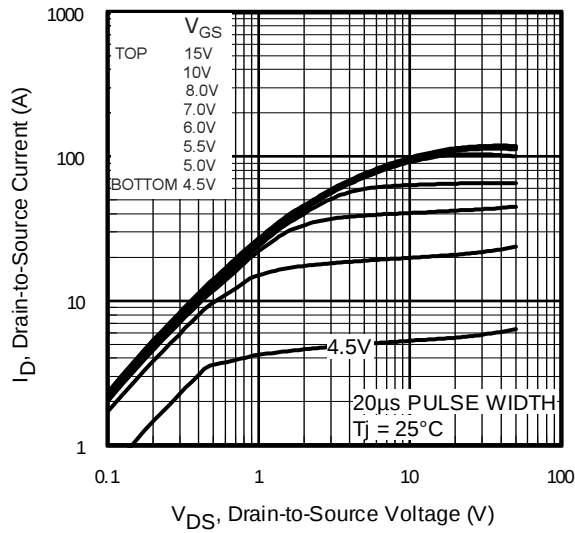


Fig 1. Typical Output Characteristics

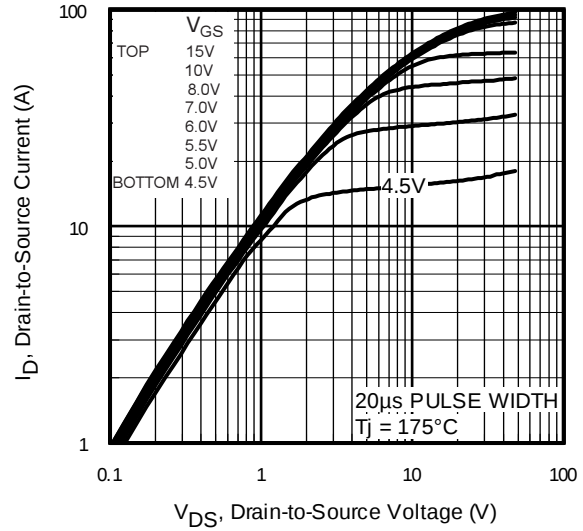


Fig 2. Typical Output Characteristics

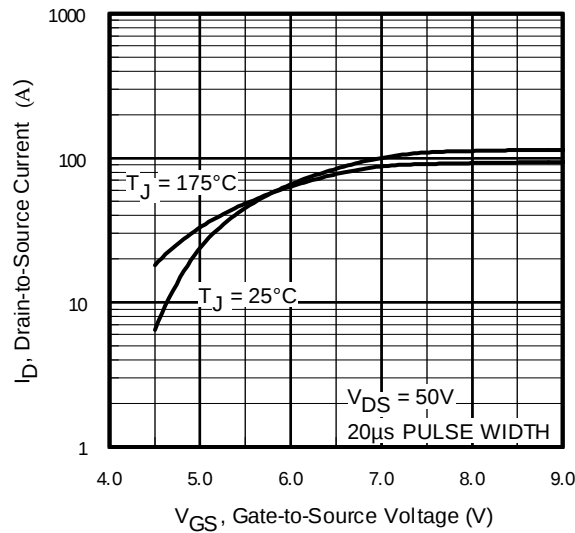


Fig 3. Typical Transfer Characteristics

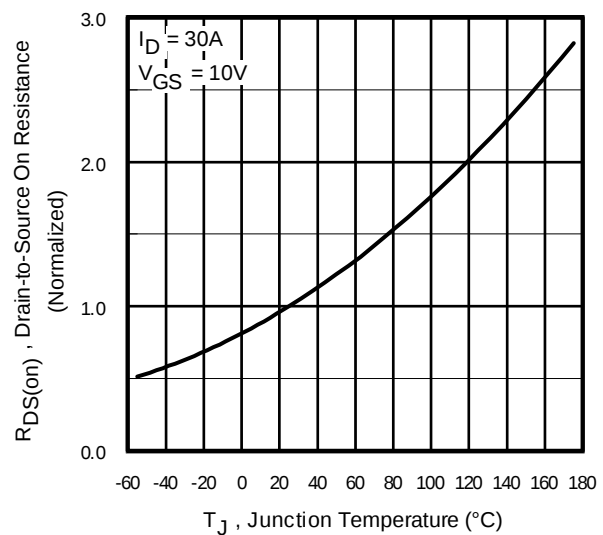


Fig 4. Normalized On-Resistance Vs. Temperature

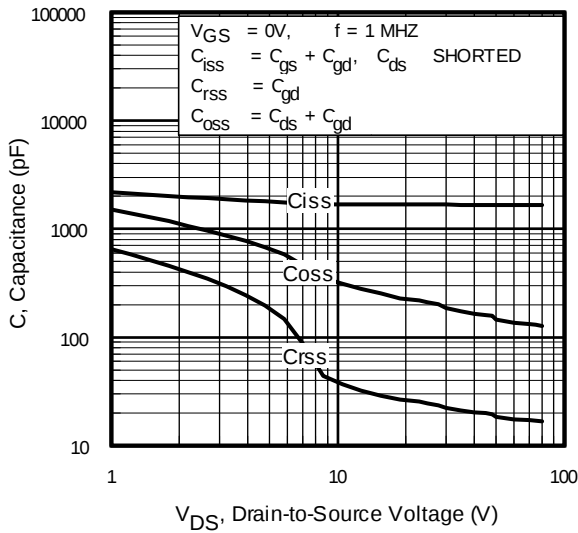


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

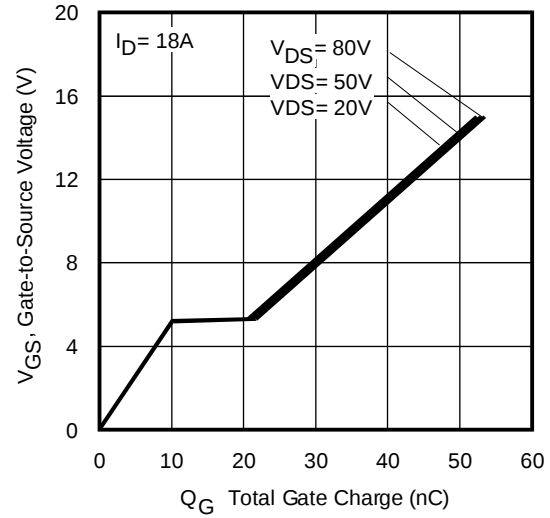


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

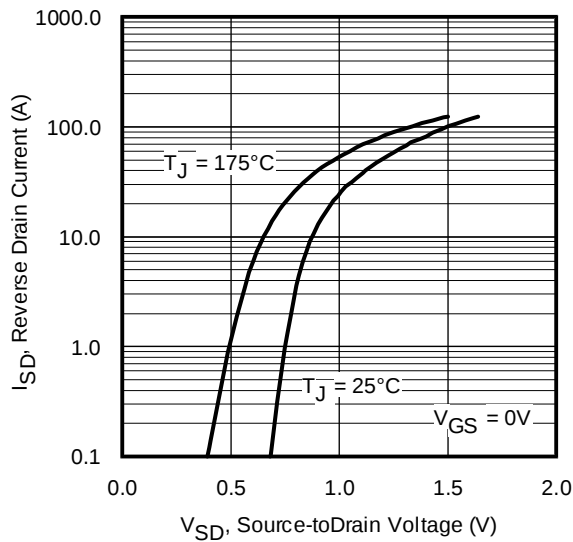


Fig 7. Typical Source-Drain Diode Forward Voltage

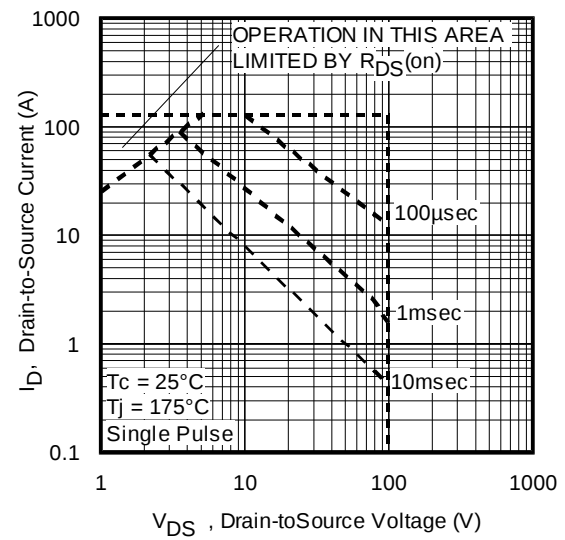


Fig 8. Maximum Safe Operating Area

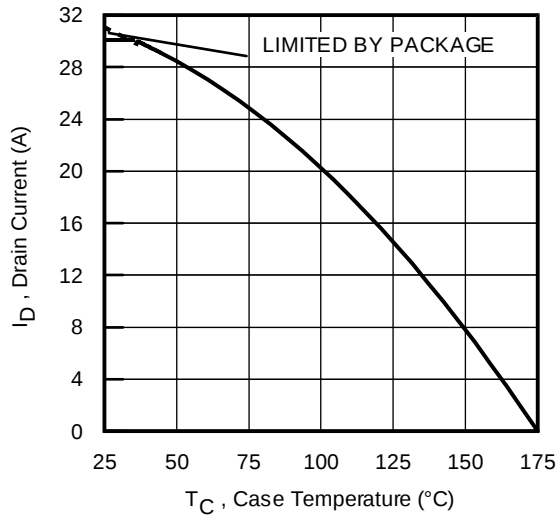


Fig 9. Maximum Drain Current Vs. Case Temperature

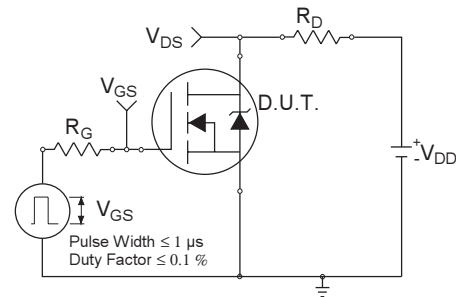


Fig 10a. Switching Time Test Circuit

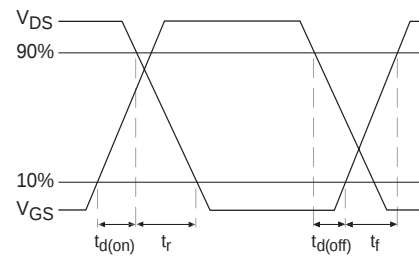


Fig 10b. Switching Time Waveforms

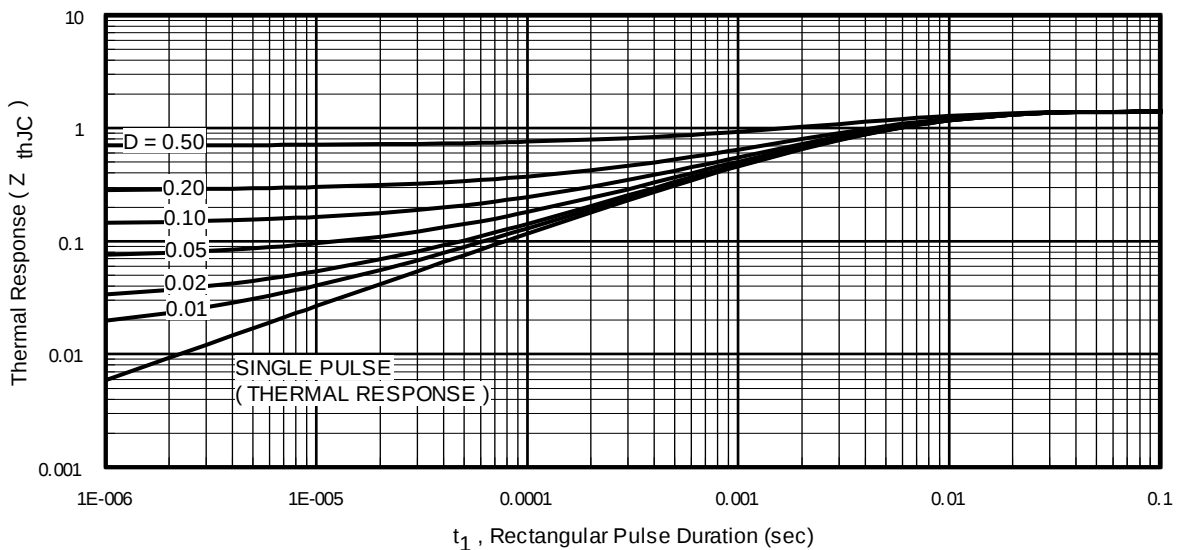


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

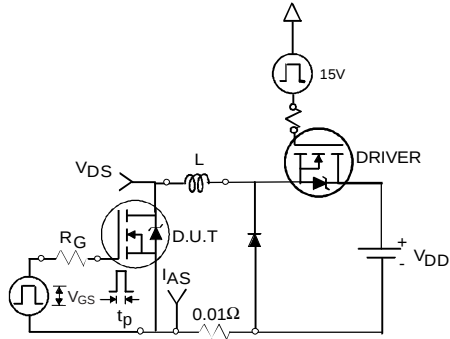


Fig 12a. Unclamped Inductive Test Circuit

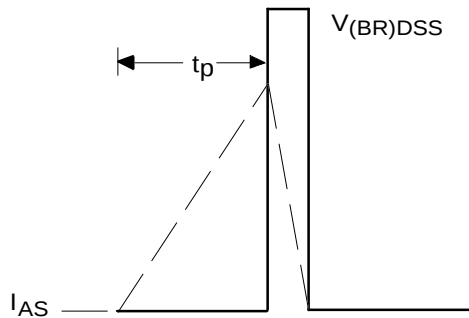


Fig 12b. Unclamped Inductive Waveforms

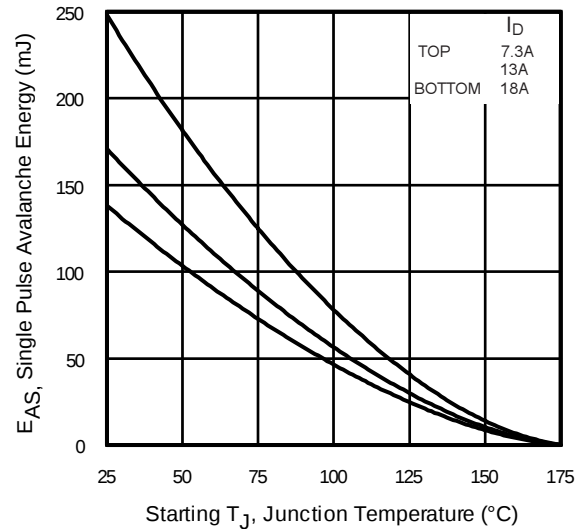


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

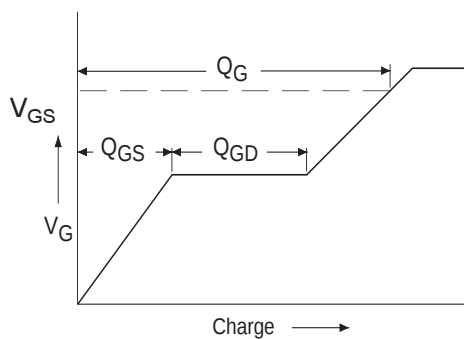


Fig 13a. Basic Gate Charge Waveform

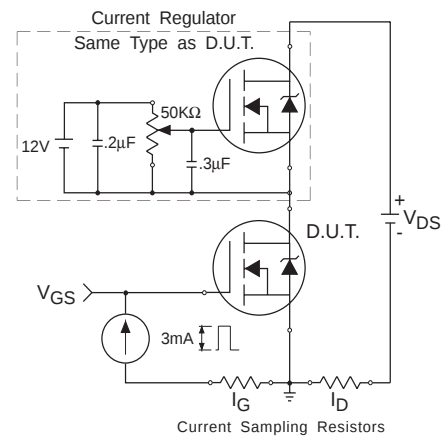
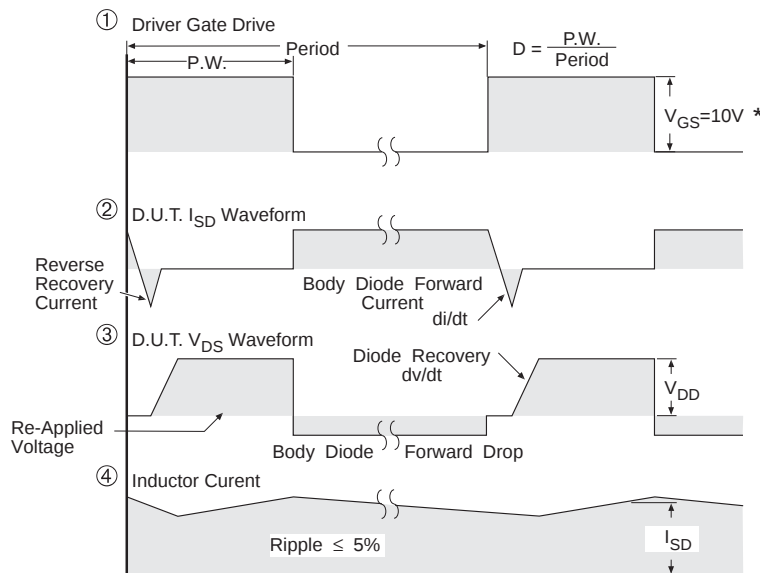
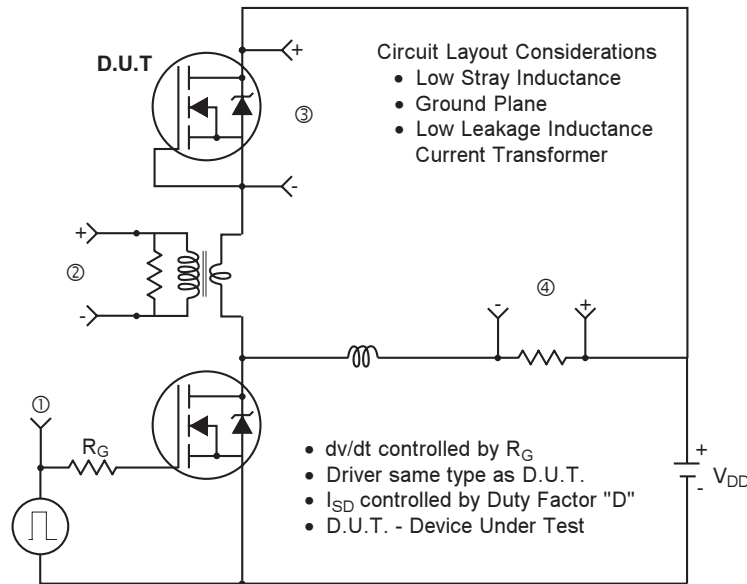


Fig 13b. Gate Charge Test Circuit

Peak Diode Recovery dv/dt Test Circuit



* $V_{GS} = 5V$ for Logic Level Devices

Fig 14. For N-Channel HEXFET® Power MOSFETs

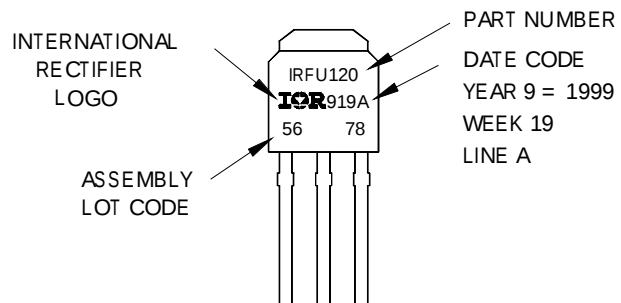
International
IOR Rectifier

Dimensions are shown in millimeters (inches)



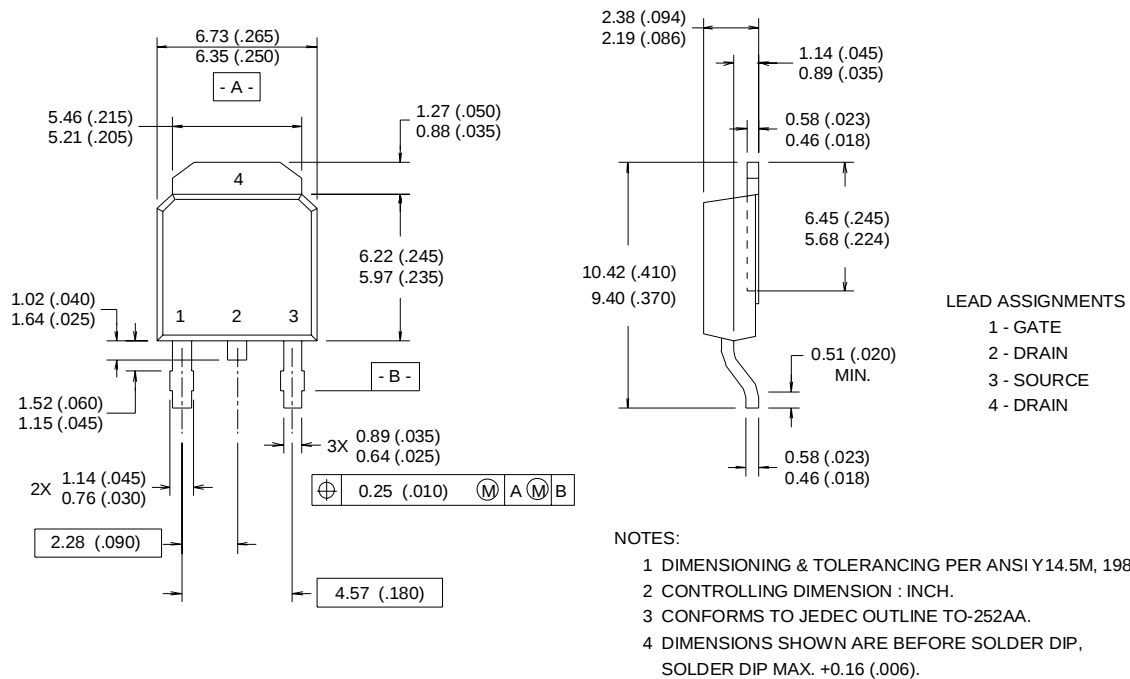
- 1 - GATE
2 - DRAIN
3 - SOURCE
4 - DRAIN

EXAMPLE: THIS IS AN IRFR120
WITH ASSEMBLY
LOT CODE 5678
ASSEMBLED ON WW 19, 1999
IN THE ASSEMBLY LINE "A"



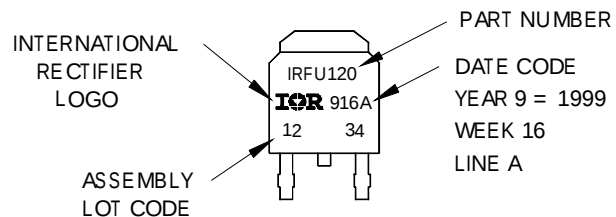
TO-252AA (D-Pak) Package Outline

Dimensions are shown in millimeters (inches)



TO-252AA (D-Pak) Part Marking Information

EXAMPLE: THIS IS AN IRFR120
WITH ASSEMBLY
LOT CODE 1234
ASSEMBLED ON WW 16, 1999
IN THE ASSEMBLY LINE "A"

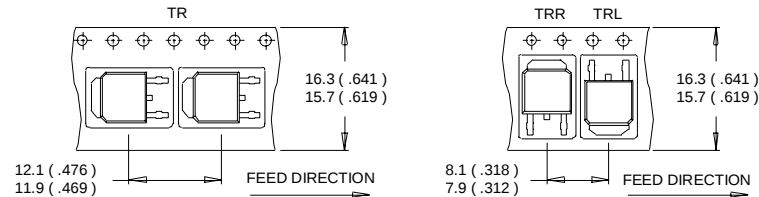


IRFR/U3410

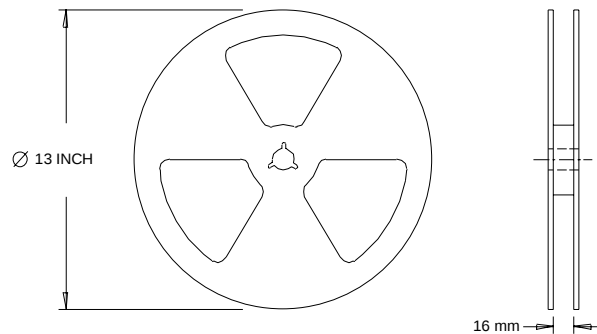
International
IR Rectifier

D-Pak (TO-252AA) Tape & Reel Information

Dimensions are shown in millimeters (inches)



- NOTES :
1. CONTROLLING DIMENSION : MILLIMETER.
 2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
 3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



- NOTES :
1. OUTLINE CONFORMS TO EIA-481.

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
 - ② Starting $T_J = 25^\circ\text{C}$, $L = 0.85\text{mH}$
 $R_G = 25\Omega$, $I_{AS} = 18\text{A}$.
 - ③ $I_{SD} \leq 18\text{A}$, $di/dt \leq 360\text{A}/\mu\text{s}$, $V_{DD} \leq V_{(BR)DSS}$,
 $T_J \leq 175^\circ\text{C}$
 - ④ Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.
 - ⑤ C_{OSS} eff. is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 80% V_{DSS}
 - ⑥ Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 30A.
- * When mounted on 1" square PCB (FR-4 or G-10 Material).
For recommended footprint and soldering techniques refer to application note #AN-994.

Data and specifications subject to change without notice.
This product has been designed and qualified for the Industrial market.
Qualification Standards can be found on IR's Web site.

International
IR Rectifier

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